Product End-of-Life Disassembly Instructions

Product Category: Notebooks

Marketing Name / Model
[List multiple models if applicable.]

HP Stream 11 Laptop PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by <em>(check all that apply with an “x” inside the “[ ]”)</em>: [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain______ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>#0 #1</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove rubber foot 2pcs.
2. Remove screw 7 pcs.
3. Disassemble the top from chassis ass’y.
4. Remove battery cable from MB connector.
5. Remove battery screw 8 pcs.
6. Remove battery pack.
7. Remove LVDS cable from MB connector.
8. Remove antenna cable from WLAN card.
9. Remove LCD module ass’y.
10. Remove speaker cable from MB connector.
11. Remove speaker screw 2 pcs.
12. Remove speaker.
13. Remove type c bracket screw 1 pcs.
14. Remove type c bracket.
15. Remove DC cable screw 1 pcs.
16. Remove DC cable from MB connector.
17. Remove USB FFC from MB & DB connector.
18. Remove MB screw 2 pcs.
19. Remove WLAN card screw 1 pcs.
20. Remove MB.
21. Remove DB screw 2 pcs.
22. Remove DB.
23. Remove POWER FFC from power board connector.
24. Remove power board screw 1 pcs.
25. Remove power board.
26. Remove KB hook screw 1 pcs.
27. Remove KB hook.
28. Remove TP FFC from touch pad connector.
29. Remove TP support bracket screw 3 pcs.
30. Remove TP support bracket.
31. Remove TP holder screw 3 pcs.
32. Remove TP holder.
33. Remove LCD module ass’y.
34. Remove LCD bezel.
35. Remove hinge cap.
36. Remove panel screw 4 pcs.
37. Remove panel.
38. Remove LVDS cable from panel connector.
39. Remove hinge screw 8 pcs.
40. Remove hinge.
41. Remove camera.
42. Remove antenna AL-foil.
43. Remove antenna.
44. END

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module

3.23 Remove service door

N/A

3.24 LCD module set disassembly

3.25 Top case disassembly
3.26 Thermal module and mother board disassembly

3.27 Bottom case disassembly